2SC5556

Silicon NPN epitaxial planar type

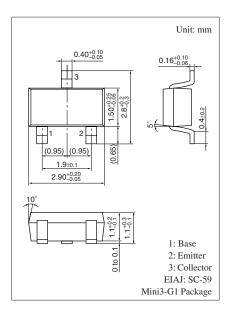
For UHF band low-noise amplification

Features

- Low noise figure NF
- \bullet High transition frequency $f_{\rm T}$
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	15	V	
Collector-emitter voltage (Base open)	V _{CEO}	10	V	
Emitter-base voltage (Collector open)	V _{EBO}	2	V	
Collector current	I _C	80	mA	
Collector power dissipation *	P _C	300	mW	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Marking Symbol: 3K

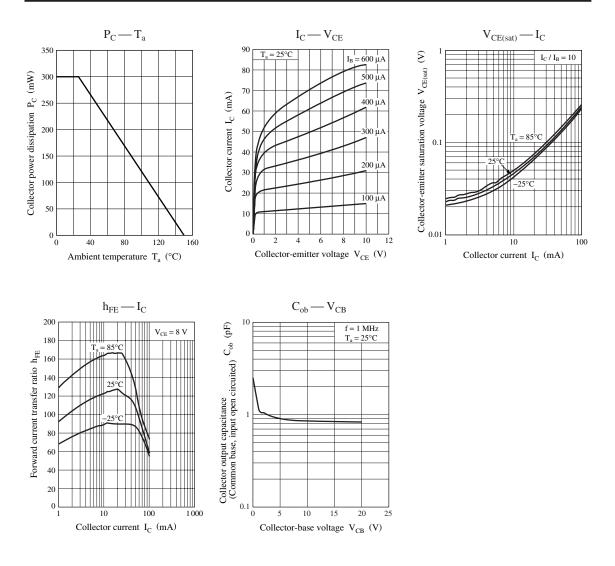
Note) *: Copper plate at the collector is more than 1 cm² in area, 1.0 mm in thickness

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{C} = 10 \ \mu A, \ I_{E} = 0$	15			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 100 \ \mu A, \ I_{\rm B} = 0$	10			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 2 V, I_C = 0$			1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}$	110		250	
Transition frequency	f _T	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 800 \text{ MHz}$	5	6		GHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		0.9	1.2	pF
Foward transfer gain	S _{21e} ²	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 800 \text{ MHz}$	7.5	10.0		dB
Maximum unilateral power gain	G _{UM}	$V_{CE} = 8 \text{ V}, \text{ I}_{C} = 20 \text{ mA}, \text{ f} = 800 \text{ MHz}$		11.5		dB
Noise figure	NF	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 800 \text{ MHz}$		1.7		dB

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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